



Agonafer Presents Seminars on Two Continents

Mechanical and Aerospace Engineering Professor Dereje Agonafer, a respected authority on the thermo-mechanical challenges of microelectronics, met with scientists and engineers on two continents in September. On September 1, he gave a presentation in Palo Alto, California at a workshop on electronics cooling organized by Hewlett Packard. On September 5, Dr. Agonafer presented an opening keynote seminar at the 17th International Symposium on Transport Phenomena held in Toyama, Japan (<http://www.pac.ne.jp/istp17/>). The participants at both events included academic and industry leaders in electronics cooling. For more information on electronic packaging research at UT Arlington, visit Dr. Agonafer's website – <http://emnspc.uta.edu>.

(Monday, Sep. 25)